

Features

- Split Gate Trench MOSFET Technology
- Very Low On-Resistance RDS(ON)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device ^(Note 1)
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

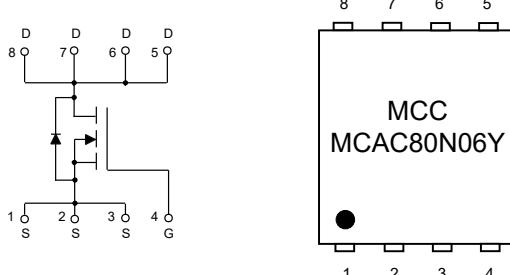
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 45°C/W Junction to Ambient(Steady-State)^(Note 2)
- Thermal Resistance: 1.47°C/W Junction to Case

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	60	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current <small>T_C=25°C</small>	I _D	80	A
		50	A
Pulsed Drain Current ^(Note 3)	I _{DM}	320	A
Total Power Dissipation ^(Note 4)	P _D	85	W
Single Pulse Avalanche Energy ^(Note 5)	E _{AS}	400	mJ

Note:

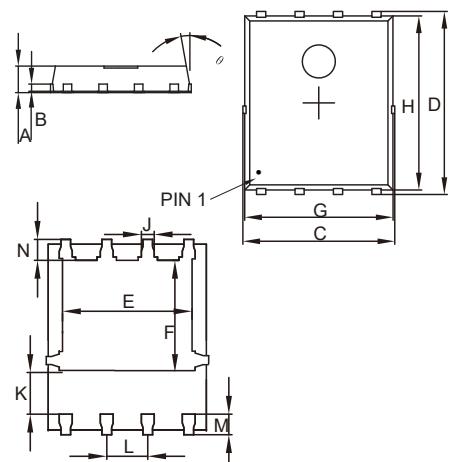
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The Power dissipation P_{DSM} is based on R_{θJA} t≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-case thermal resistance.
5. T_J=25°C, V_{DD}=40V, V_G=10V, L=2mH.

Internal Structure and Marking Code



N-CHANNEL MOSFET

DFN5060

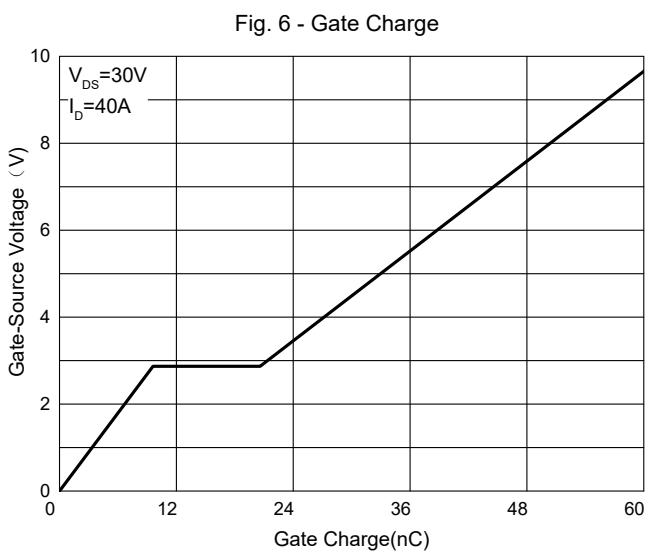
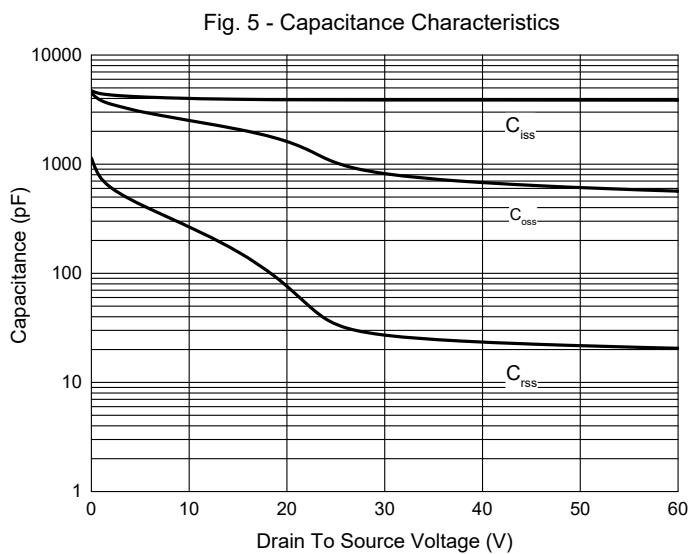
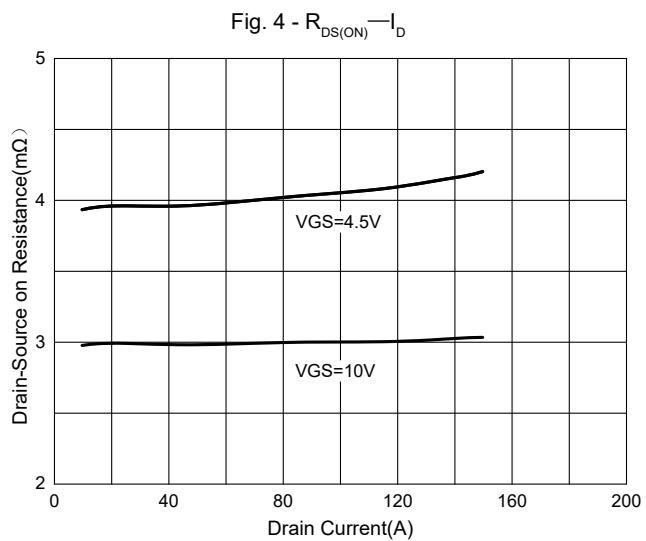
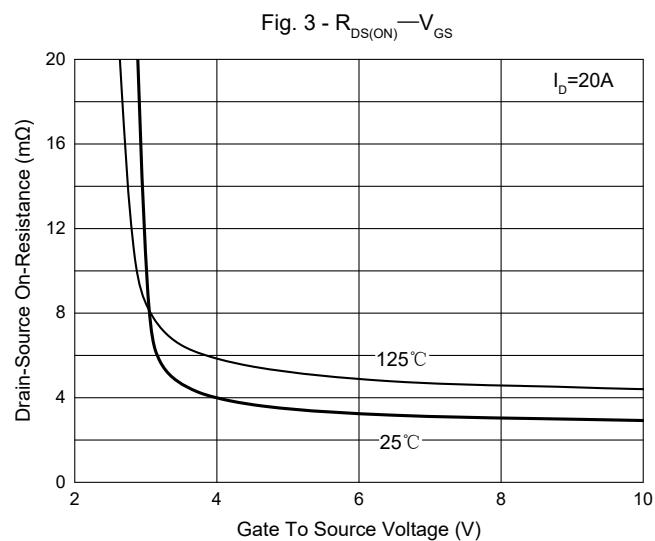
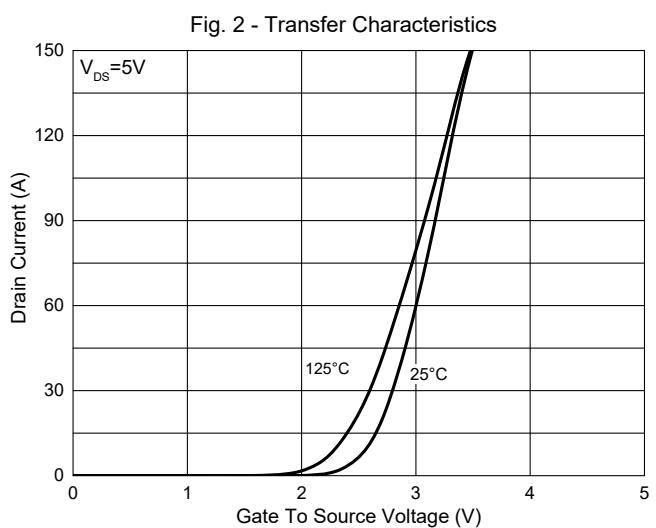
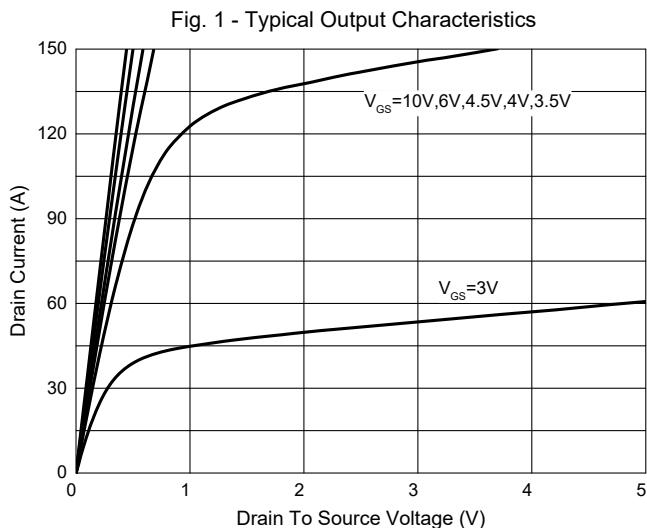


DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.031	0.047	0.80	1.20	
B	0.010		0.254		TYP.
C	0.193	0.222	4.90	5.64	
D	0.232	0.250	5.90	6.35	
E	0.148	0.167	3.75	4.25	
F	0.126	0.154	3.20	3.92	
G	0.189	0.213	4.80	5.40	
H	0.222	0.239	5.65	6.06	
K	0.045	0.059	1.15	1.50	
J	0.012	0.020	0.30	0.50	
L	0.046	0.054	1.17	1.37	
M	0.012	0.028	0.30	0.71	
N	0.016	0.028	0.40	0.71	

Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	60	65		V
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=60V, V_{GS}=0V$			1	μA
		$V_{DS}=60V, V_{GS}=0V, T_J=55^\circ C$			5	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.2	1.7	2.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$		3.0	4.2	$m\Omega$
		$V_{GS}=4.5V, I_D=10A$		3.9	5.2	
Gate Resistance	R_g	$V_{DS}=0V, V_{GS}=0V, f=1MHz$		0.8		Ω
Dynamic Characteristics						
Continuous Body Diode Current	I_S				80	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=20A$		0.85	1.3	V
Reverse Recovery Charge	Q_{rr}	$I_F=I_S, di/dt=100A/\mu s$		58		nC
Reverse Recovery Time	t_{rr}			52		ns
Switching Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=30V, V_{GS}=0V, f=1MHz$		3783		pF
Output Capacitance	C_{oss}			810		
Reverse Transfer Capacitance	C_{rss}			26		
Total Gate Charge	Q_g	$V_{DS}=30V, V_{GS}=4.5V, I_D=40A$		30		nC
Total Gate Charge	Q_g			62		
Gate-Source Charge	Q_{gs}			9.6		
Gate-Drain Charge	Q_{gd}			11		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=10V, V_{DS}=15V, R_L=2.5\Omega, R_{GEN}=3\Omega, I_D=6A$		13.4		ns
Turn-On Rise Time	t_r			12		
Turn-Off Delay Time	$t_{d(off)}$			46		
Turn-Off Fall Time	t_f			12		

Curve Characteristics



Curve Characteristics

Fig. 7 - Nominalized Threshold voltage

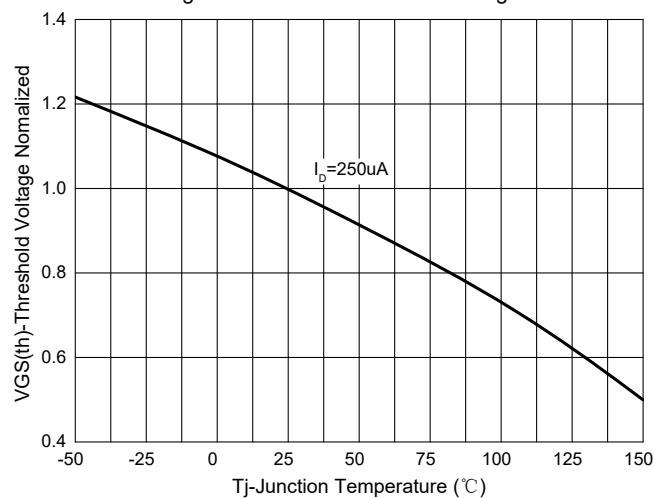


Fig.8-Normalized On Resistance Characteristics

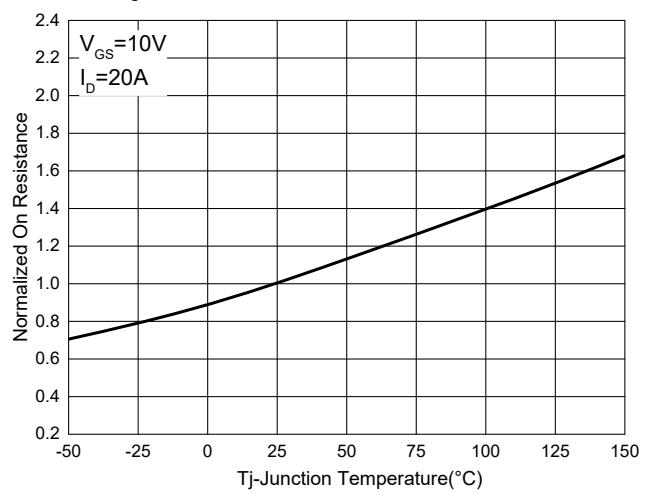


Fig.9 - $I_s - V_{SD}$

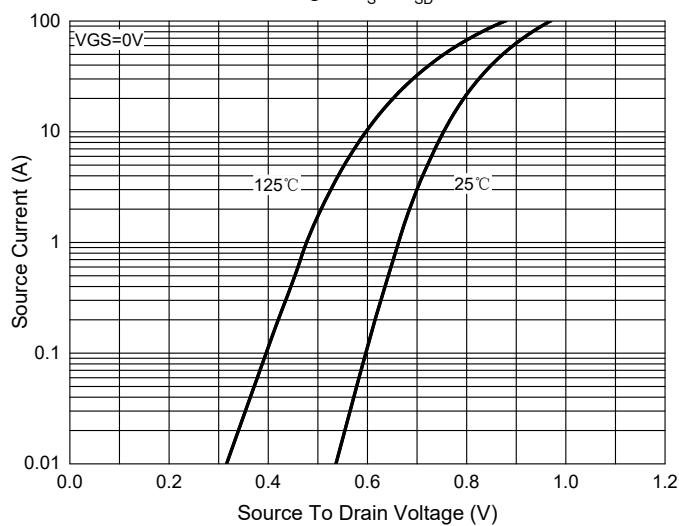


Fig. 10 - Drain Current

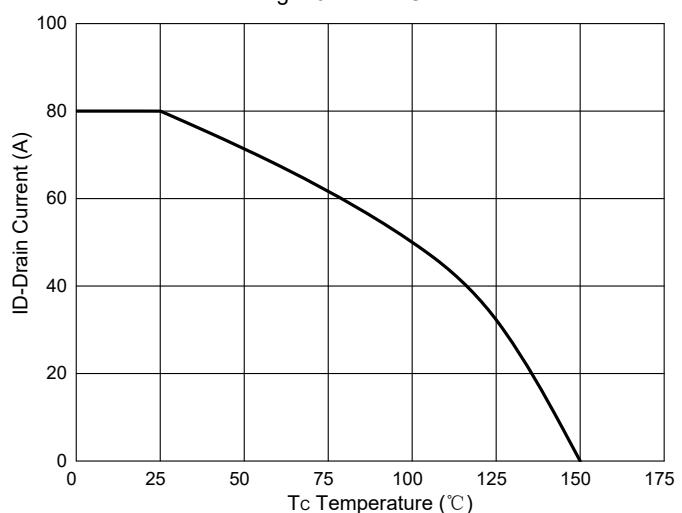
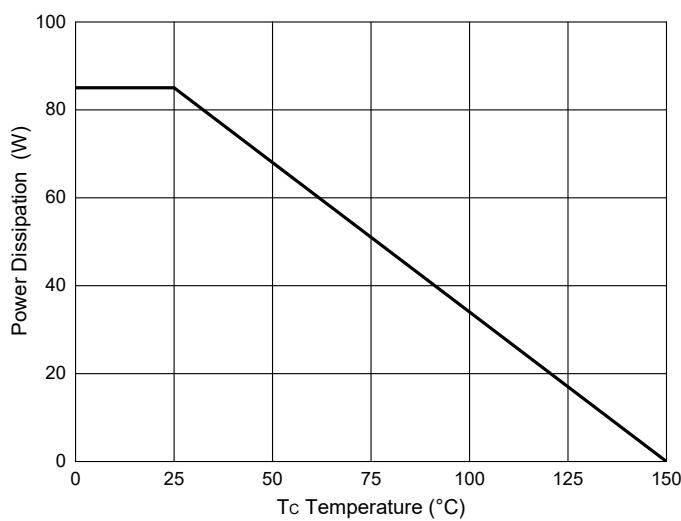


Fig.11-PD Dissipation



Curve Characteristics

Fig. 12 - Safe Operation Area

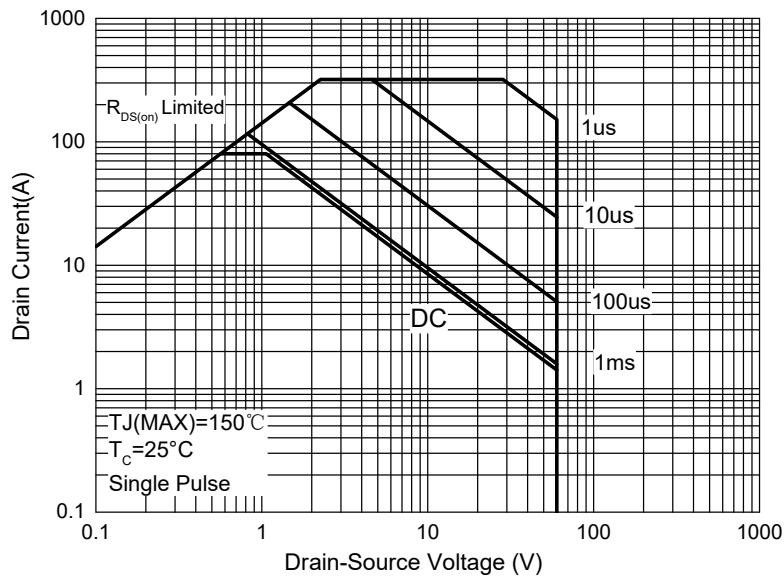
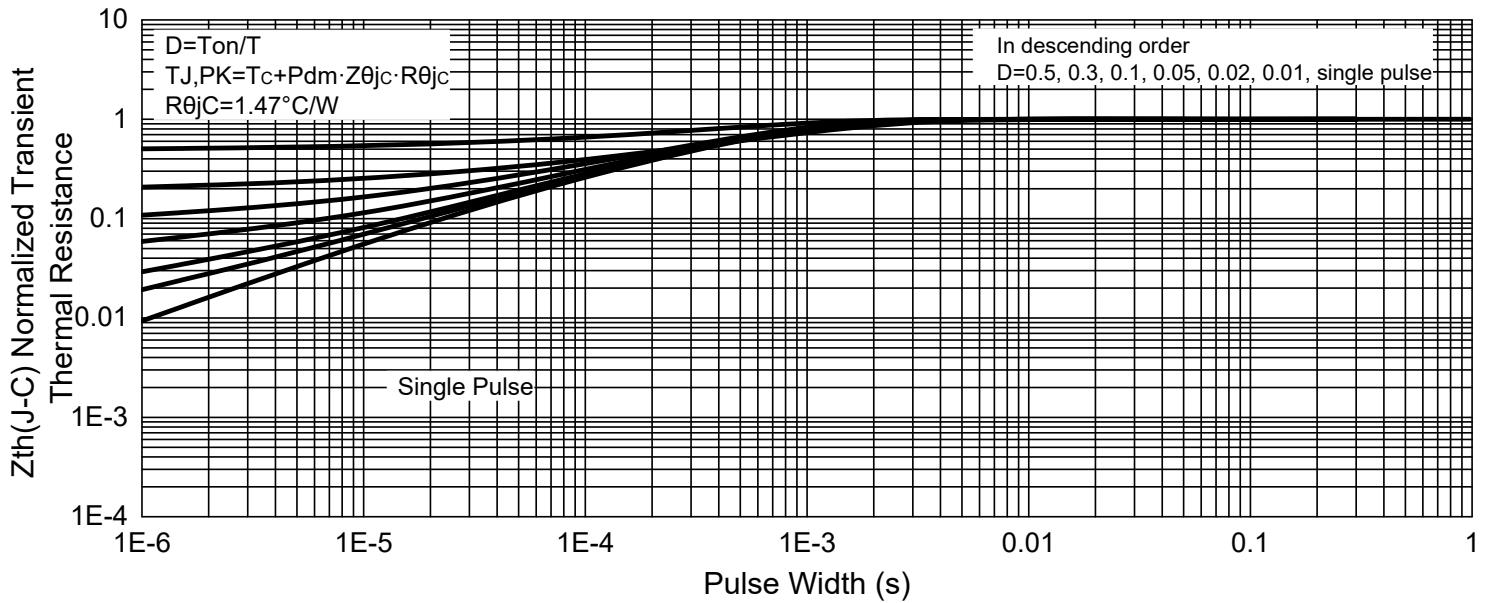


Fig. 13 -Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 5Kpcs/Reel

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